BAV99 series
High-speed switching diodes

Rev. 8 — 18 November 2010   **Product data sheet**

1. Product profile

1.1 General description

High-speed switching diodes, encapsulated in small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package			Configuration	Package configuration
	NXP	**JEITA**	**JEDEC**		
BAV99	SOT23	-	TO-236AB	dual series	small
BAV99S	SOT363	SC-88	-	quadruple; 2 series	very small
BAV99W	SOT323	SC-70	-	dual series	very small

1.2 Features and benefits

- High switching speed: $t_{rr} \leq 4$ ns
- Low leakage current
- Small SMD plastic packages
- Low capacitance: $C_d \leq 1.5$ pF
- Reverse voltage: $V_R \leq 100$ V
- AEC-Q101 qualified

1.3 Applications

- High-speed switching
- General-purpose switching
- Reverse polarity protection

1.4 Quick reference data
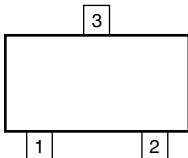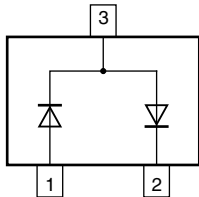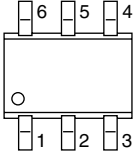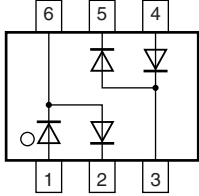
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
I_R	reverse current	$V_R = 80$ V	-	-	0.5	μA
V_R	reverse voltage		-	-	100	V
t_{rr}	reverse recovery time	[1]	-	-	4	ns

[1] When switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100$ Ω; measured at $I_R = 1$ mA.

2. Pinning information

Table 3.   Pinning

Pin	Description	Simplified outline	Graphic symbol
BAV99; BAV99W			
1	anode (diode 1)		
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		

006aaa144

006aaa763

Pin	Description	Simplified outline	Graphic symbol
BAV99S			
1	anode (diode 1)		
2	cathode (diode 2)		
3	cathode (diode 3), anode (diode 4)		
4	anode (diode 3)		
5	cathode (diode 4)		
6	cathode (diode 1), anode (diode 2)		

006aab101

3. Ordering information

Table 4.   Ordering information

Type number	Package			
	Name	Description		Version
BAV99	-	plastic surface-mounted package; 3 leads		SOT23
BAV99S	SC-88	plastic surface-mounted package; 6 leads		SOT363
BAV99W	SC-70	plastic surface-mounted package; 3 leads		SOT323

4. Marking

Table 5.   Marking codes

Type number	Marking code[1]
BAV99	A7*
BAV99S	K1*
BAV99W	A7*

[1]   * = placeholder for manufacturing site code

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5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V_{RRM}	repetitive peak reverse voltage			-	100	V
V_R	reverse voltage			-	100	V
I_F	forward current					
	BAV99		[1]	-	215	mA
			[2]	-	125	mA
	BAV99S		[1]	-	200	mA
	BAV99W		[1]	-	150	mA
			[2]	-	130	mA
I_{FRM}	repetitive peak forward current			-	500	mA
I_{FSM}	non-repetitive peak forward current	square wave	[3]			
		t_p = 1 μs		-	4	A
		t_p = 1 ms		-	1	A
		t_p = 1 s		-	0.5	A
P_{tot}	total power dissipation		[1][4]			
	BAV99	$T_{amb} \leq 25$ °C		-	250	mW
	BAV99S	$T_{sp} \leq 85$ °C	[5]	-	250	mW
	BAV99W	$T_{amb} \leq 25$ °C		-	200	mW
Per device						
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−65	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] Single diode loaded.

[2] Double diode loaded.

[3] T_j = 25 °C prior to surge.

[4] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[5] Soldering points at pins 2, 3, 5 and 6.

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6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]			
	BAV99		-	-	500	K/W
	BAV99W		-	-	625	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point					
	BAV99		-	-	360	K/W
	BAV99S	[3]	-	-	260	K/W
	BAV99W		-	-	300	K/W

[1] Single diode loaded.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Soldering points at pins 2, 3, 5 and 6.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\ °C$ unless otherwise specified.

| Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	$I_F = 1$ mA	-	-	715	mV
		$I_F = 10$ mA	-	-	855	mV
		$I_F = 50$ mA	-	-	1	V
		$I_F = 150$ mA	-	-	1.25	V
I_R	reverse current	$V_R = 25$ V	-	-	30	nA
		$V_R = 80$ V	-	-	0.5	μA
		$V_R = 25$ V; $T_j = 150\ °C$	-	-	30	μA
		$V_R = 80$ V; $T_j = 150\ °C$	-	-	50	μA
C_d	diode capacitance	$f = 1$ MHz; $V_R = 0$ V	-	-	1.5	pF
t_{rr}	reverse recovery time	[1]	-	-	4	ns
V_{FR}	forward recovery voltage	[2]	-	-	1.75	V

[1] When switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100\ \Omega$; measured at $I_R = 1$ mA.

[2] When switched from $I_F = 10$ mA; $t_r = 20$ ns.

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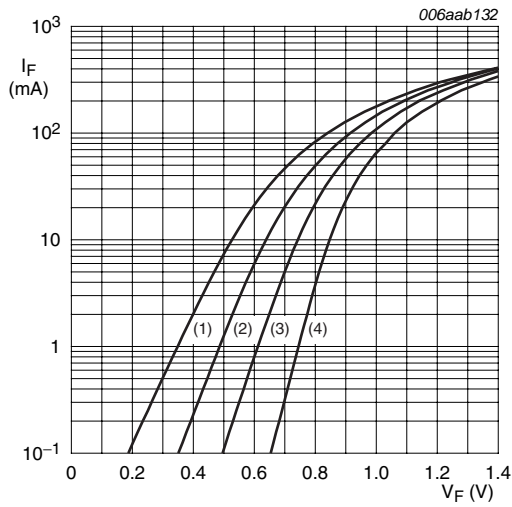
(1) T_{amb} = 150 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C
(4) T_{amb} = −40 °C

Fig 1. Forward current as a function of forward voltage; typical values
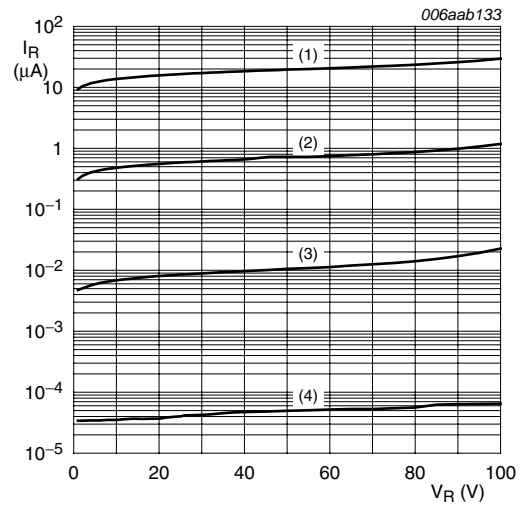
(1) T_{amb} = 150 °C
(2) T_{amb} = 85 °C
(3) T_{amb} = 25 °C
(4) T_{amb} = −40 °C

Fig 2. Reverse current as a function of reverse voltage; typical values
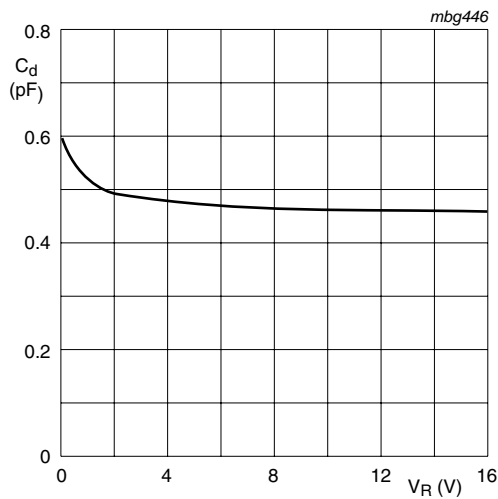
f = 1 MHz; T_{amb} = 25 °C

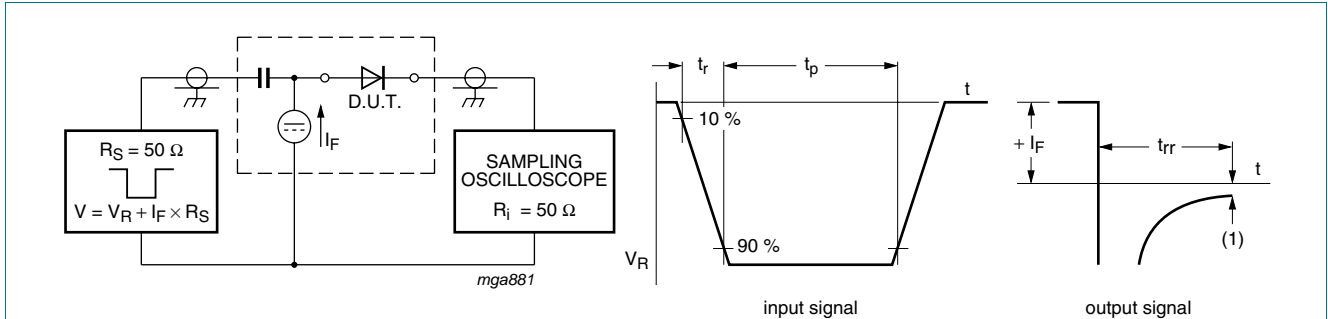**Fig 3. Diode capacitance as a function of reverse voltage; typical values**
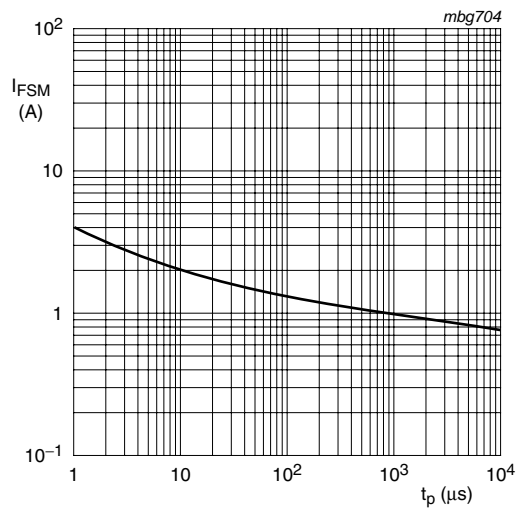
Based on square wave currents.

T_j = 25 °C; prior to surge

Fig 4. Non-repetitive peak forward current as a function of pulse duration; maximum values
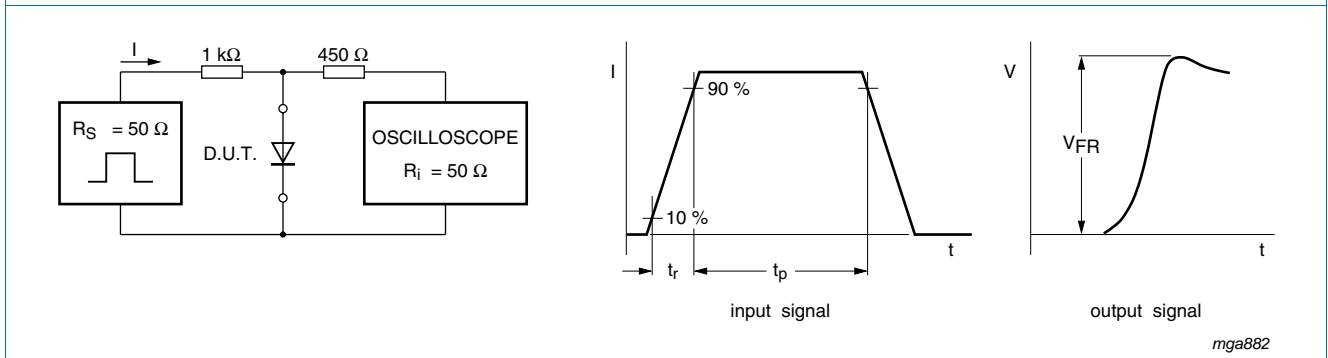
8. Test information

(1) $I_R = 1$ mA

Input signal: reverse pulse rise time $t_r = 0.6$ ns; reverse voltage pulse duration $t_p = 100$ ns; duty cycle $\delta = 0.05$

Oscilloscope: rise time $t_r = 0.35$ ns

**Fig 5. Reverse recovery time test circuit and waveforms**

Input signal: forward pulse rise time $t_r = 20$ ns; forward current pulse duration $t_p \geq 100$ ns; duty cycle $\delta \leq 0.005$

Fig 6. Forward recovery voltage test circuit and waveforms

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

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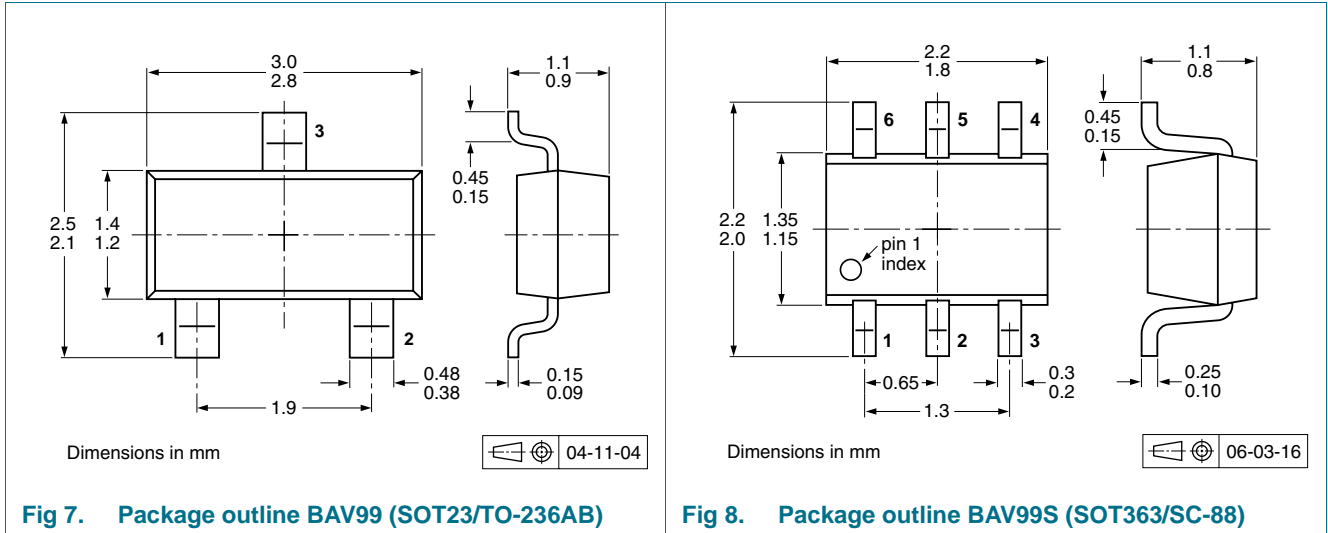
9. Package outline

Fig 7. Package outline BAV99 (SOT23/TO-236AB)

Fig 8. Package outline BAV99S (SOT363/SC-88)
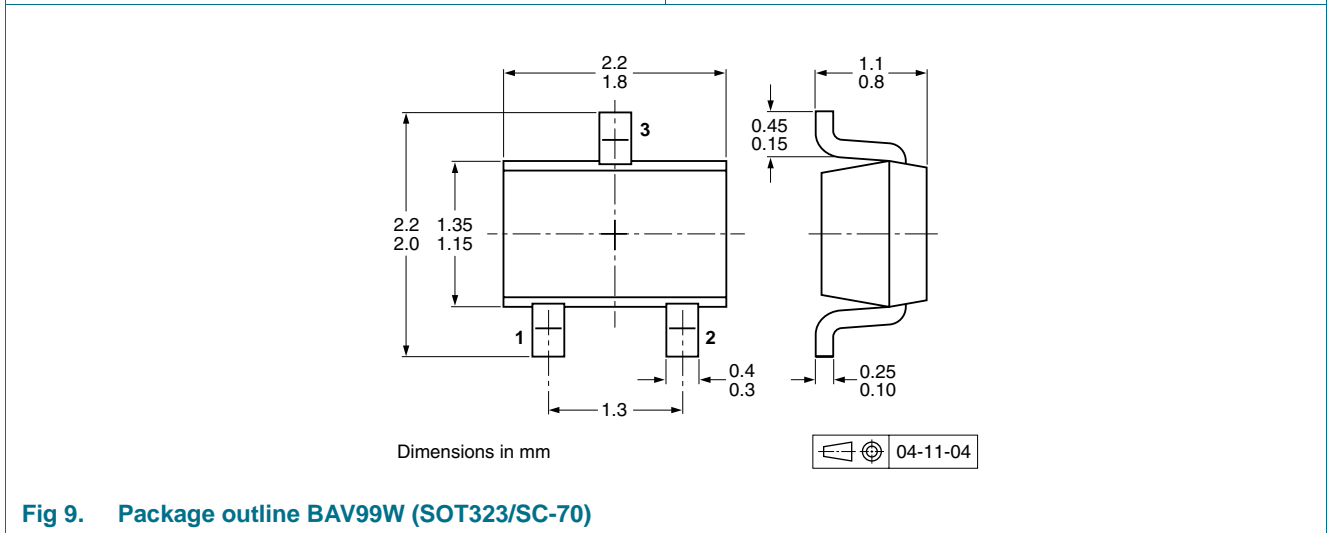
Fig 9. Package outline BAV99W (SOT323/SC-70)

10. Packing information

Table 9. Packing methods

*The indicated -xxx are the last three digits of the 12NC ordering code.*[1]

Type number	Package	Description		Packing quantity	
				3000	**10000**
BAV99	SOT23	4 mm pitch, 8 mm tape and reel		-215	-235
BAV99S	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-165
BAV99W	SOT323	4 mm pitch, 8 mm tape and reel		-115	-135

[1] For further information and the availability of packing methods, see Section 14.
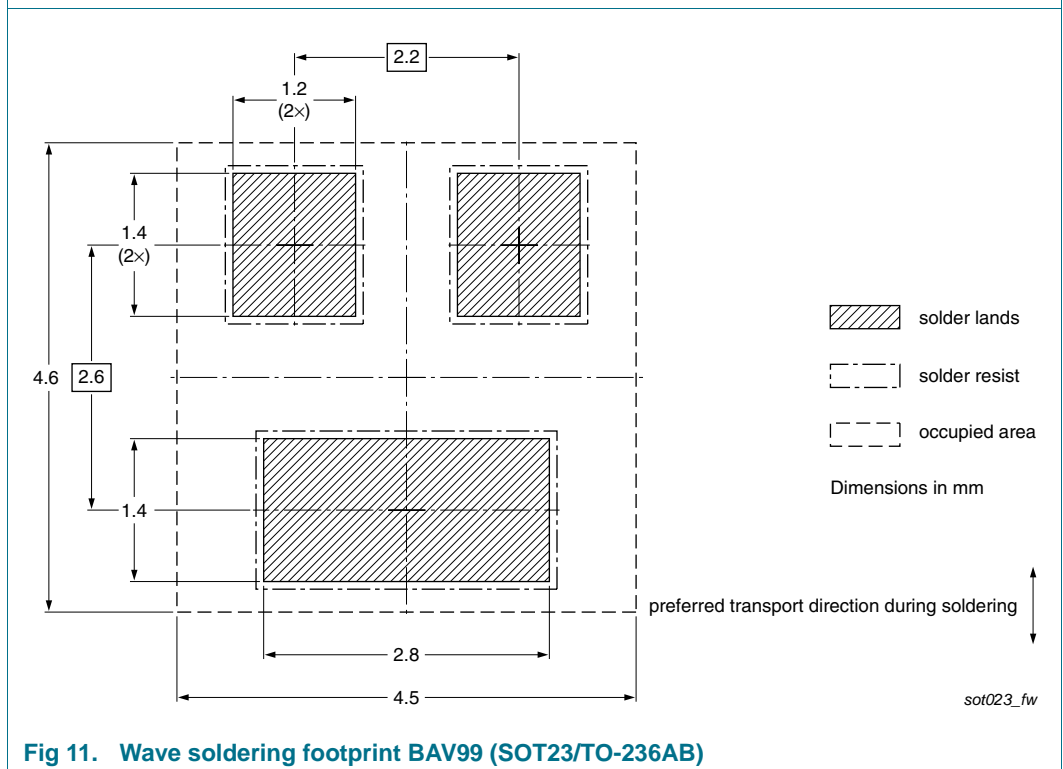
[2] T1: normal taping

[3] T2: reverse taping

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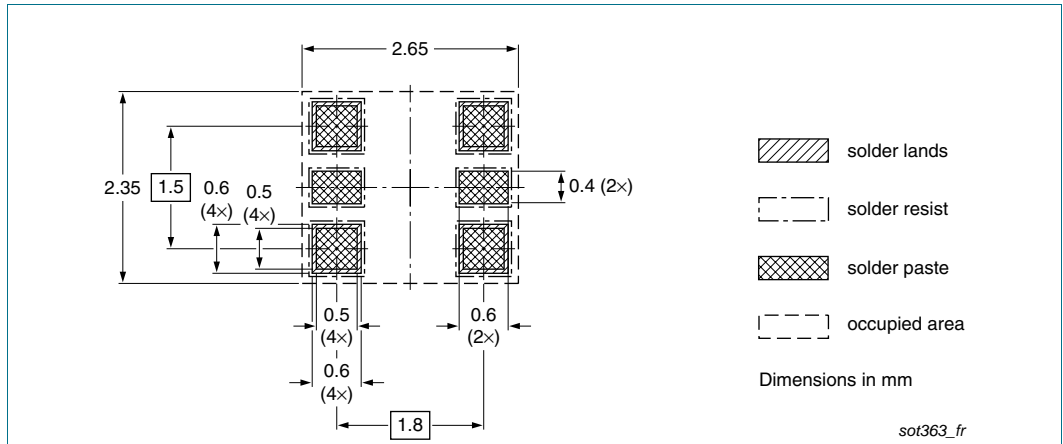
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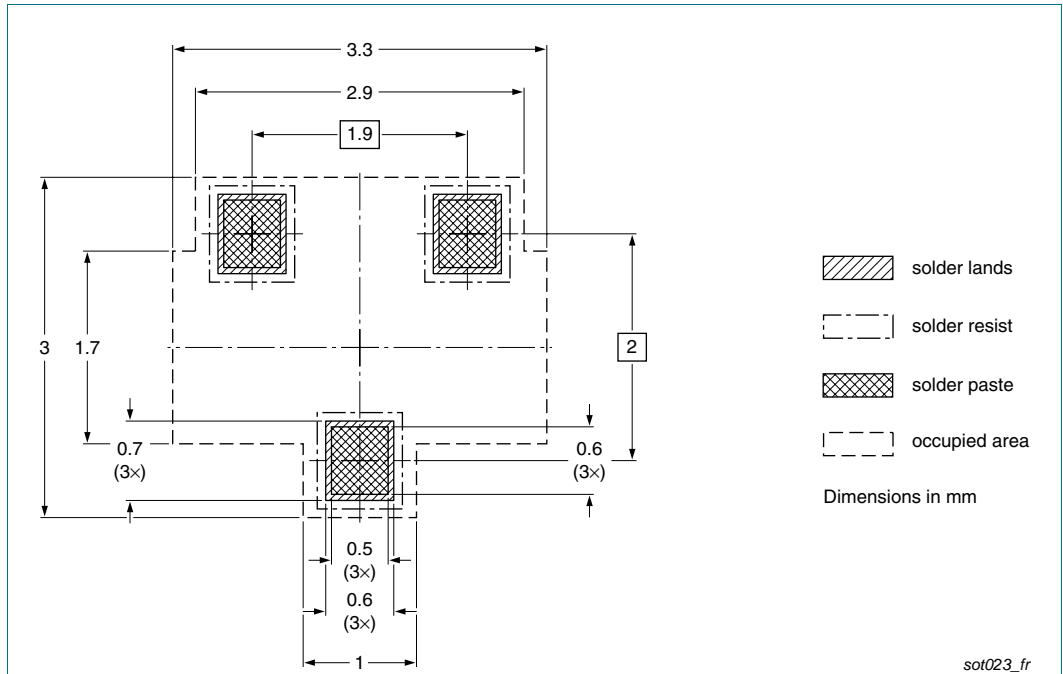
11. Soldering

Fig 10. Reflow soldering footprint BAV99 (SOT23/TO-236AB)

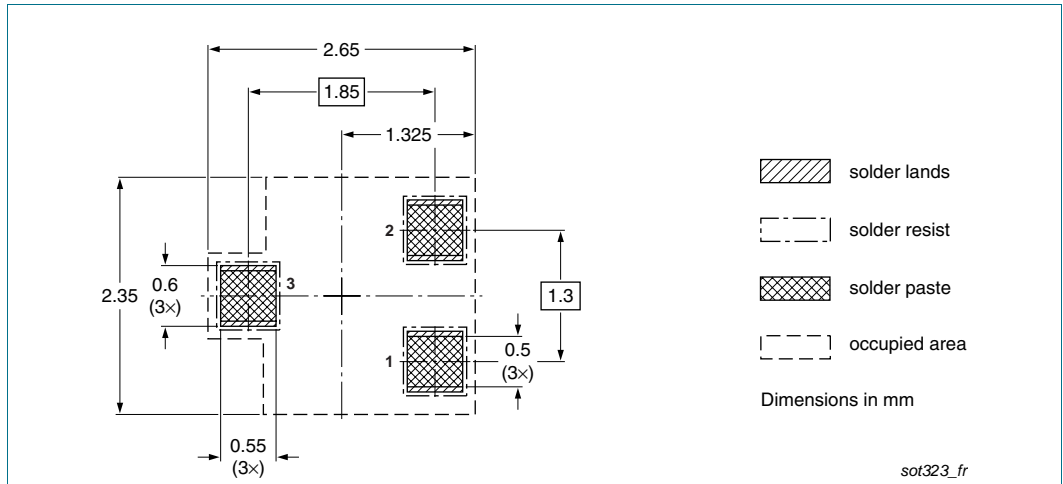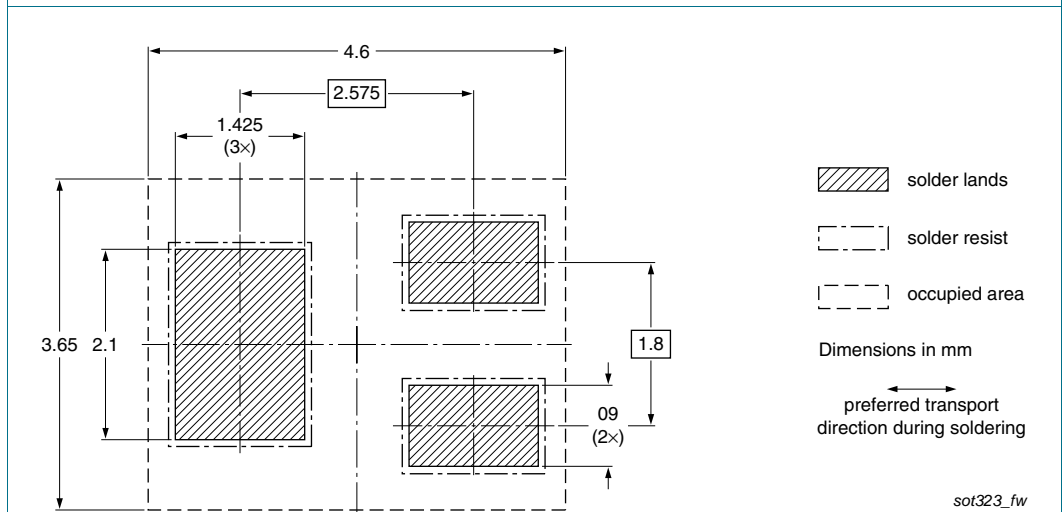**Fig 11. Wave soldering footprint BAV99 (SOT23/TO-236AB)**

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solder lands

solder resist

solder paste

occupied area

Dimensions in mm

sot363_fr

Fig 12. Reflow soldering footprint BAV99S (SOT363/SC-88)

solder lands

solder resist

occupied area

Dimensions in mm

preferred transport
direction during soldering

sot363_fw

Fig 13. Wave soldering footprint BAV99S (SOT363/SC-88)

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Fig 14. Reflow soldering footprint BAV99W (SOT323/SC-70)

Fig 15. Wave soldering footprint BAV99W (SOT323/SC-70)

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12. Revision history

Table 10.　Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAV99_SER_8	20101118	Product data sheet	-	BAV99_SER_7
Modifications:	• Section 4 "Marking": marking placeholder explanation in table footer updated • Section 5 "Limiting values": P_{tot} condition for BAV99S corrected • Section 13 "Legal information": updated			
BAV99_SER_7	20100414	Product data sheet	-	BAV99_SER_6
BAV99_SER_6	20100310	Product data sheet	-	BAV99_SER_5
BAV99_SER_5	20080820	Product data sheet	-	BAV99_4 BAV99S_3 BAV99W_4
BAV99_4	20011015	Product specification	-	BAV99_3
BAV99S_3	20010514	Product specification	-	BAV99S_N_2
BAV99W_4	19990511	Product specification	-	BAV99W_3

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13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

13.4   Trademarks

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15. Contents

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